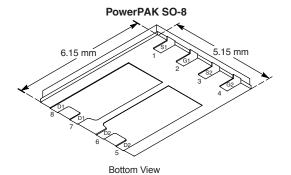


# **Dual N-Channel 100-V (D-S) MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)		
100	0.049 at V <sub>GS</sub> = 10 V	5.9		
	0.060 at V <sub>GS</sub> = 6 V	5.5		



Ordering Information: Si7942DP-T1-E3 (Lead (Pb)-free)

Si7942DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

### **FEATURES**

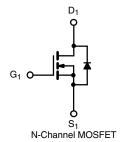
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Power MOSFETs
- New Low Thermal Resistance PowerPAK<sup>®</sup> Package
- Dual MOSFET for Space Savings

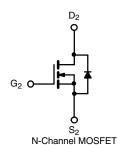




### **APPLICATIONS**

- Synchronous Buck Shoot-Through Resistant
- · Optimized for Primary Side Switch





ABSOLUTE MAXIMUM RATINGS TA	$_{\lambda}$ = 25 °C, unles	ss otherwise n	oted		
Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		$V_{DS}$	100		V
Gate-Source Voltage		$V_{GS}$	:	V	
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	5.9	3.8	
Continuous Drain Current (1) = 150 °C)	T <sub>A</sub> = 70 °C		4.7	3.0	
Pulsed Drain Current		I <sub>DM</sub>	20		Α
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	2.9	1.2	
Single Avalanche Current L = 0.1 mH		I <sub>AS</sub>	20		
Single Avalanche Energy		E <sub>AS</sub>	20		mJ
Manianum Danian Disabantian d	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.5	1.4	W
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	' Б	2.2	0.9	VV
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C
Soldering Recommendations (Peak Temperature)b, c		260			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Manifesture Instantanta Ambienti	t ≤ 10 s	R <sub>thJA</sub>	26	35		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	' 'thJA	60	85	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	$R_{thJC}$	2.2	2.7		

#### Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See Solder Profile (<a href="https://www.vishay.com/ppg?73257">www.vishay.com/ppg?73257</a>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

# Vishay Siliconix



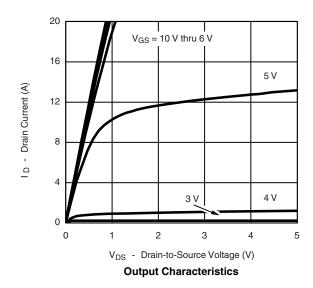
<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4.0	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zoro Coto Voltogo Droin Current	l	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α
	В	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.9 A	10 V, I <sub>D</sub> = 5.9 A		0.049	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 6 \text{ V}, I_D = 5.5 \text{ A}$		0.048	0.060	Ω
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 5.9 A		14		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 2.9 \text{ A}, V_{GS} = 0 \text{ V}$		0.77	1.2	V
Dynamic <sup>b</sup>						
Total Gate Charge	$Q_g$			16	24	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5.9 \text{ A}$		3.8		nC
Gate-Drain Charge	$Q_{gd}$			5.5		
Gate Resistance	$R_g$			2.2		Ω
Turn-On Delay Time	t <sub>d(on)</sub>			15	25	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 50 $\Omega$		15	25	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ 1 A, $V_{GEN}$ = 10 V, $R_g$ = 6 $\Omega$		35	55	ns
Fall Time	t <sub>f</sub>			20	30	.10
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 2.9 A, dI/dt = 100 A/μs		50	75	

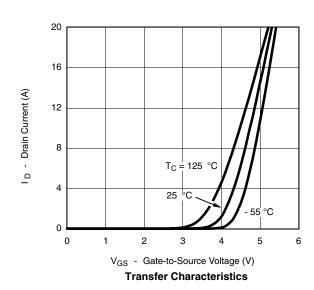
### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



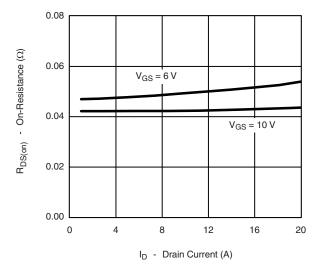




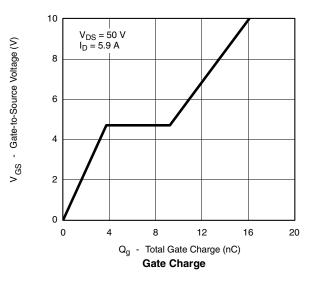


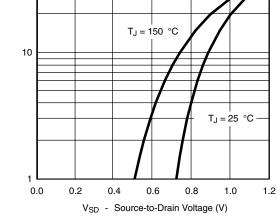


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

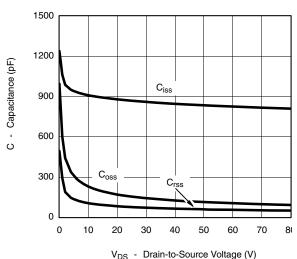


On-Resistance vs. Drain Current



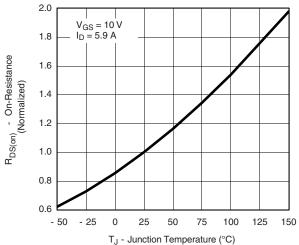


Source-Drain Diode Forward Voltage

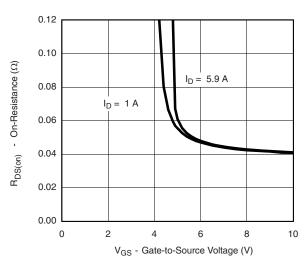


V<sub>DS</sub> - Drain-to-Source voltage (v)





**On-Resistance vs. Junction Temperature** 



On-Resistance vs. Gate-to-Source Voltage

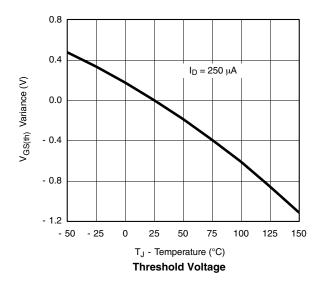
40

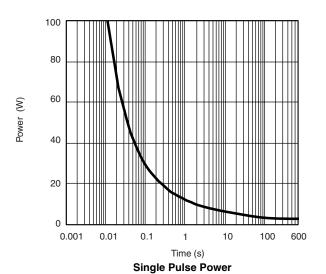
- Source Current (A)

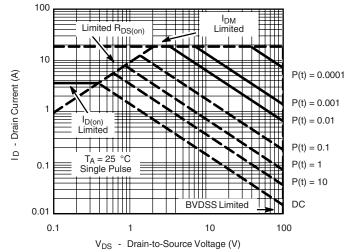
## Vishay Siliconix

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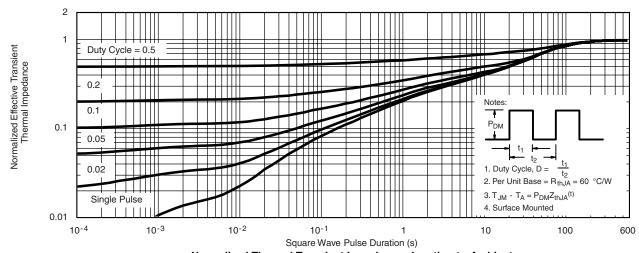
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







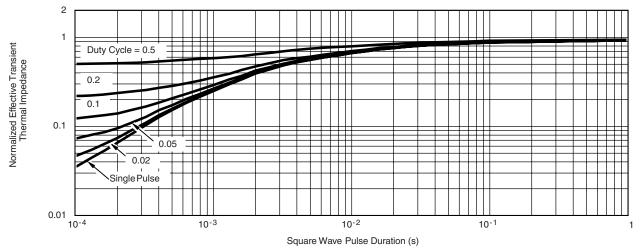
Safe Operating Area, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



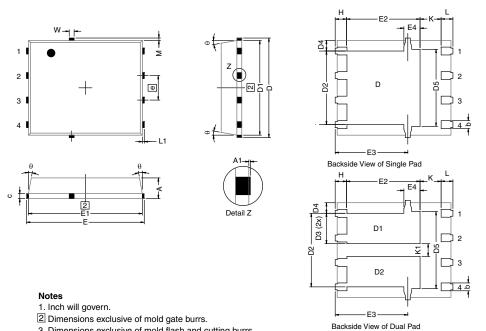
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?72118">www.vishay.com/ppg?72118</a>.



DWG: 5881

# PowerPAK® SO-8, (Single/Dual)



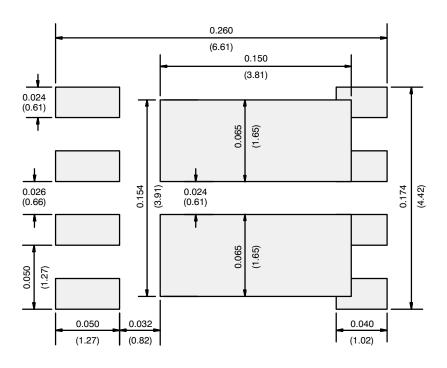
3. Dimensions exclusive of mold flash and cutting burrs.							
DIM.		MILLIMETERS		INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
	4.00	4.00	F 00	0.400	0.400	0.407	

Α	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.56	3.76	3.91	0.140	0.148	0.154	
D3	1.32	1.50	1.68	0.052	0.059	0.066	
D4		0.57 typ.			0.0225 typ.		
D5		3.98 typ.			0.157 typ.		
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	5.79	5.89	5.99	0.228	0.232	0.236	
E2 (for AL product)	3.30	3.48	3.66	0.130	0.137	0.144	
E2 (for other product)	3.48	3.66	3.84	0.137	0.144	0.151	
E3	3.68	3.78	3.91	0.145	0.149	0.154	
E4 (for AL product)		0.58 typ.			0.023 typ.		
E4 (for other product)		0.75 typ.		0.030 typ.			
е		1.27 BSC		0.050 BSC			
K (for AL product)		1.45 typ.		0.057 typ.			
K (for other product)		1.27 typ.		0.050 typ.			
K1	0.56	-	=	0.022	-	=	
Н	0.51	0.61	0.71	0.020	0.024	0.028	
L	0.51	0.61	0.71	0.020	0.024	0.028	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
M	0.125 typ.			0.005 typ.			
ECN: C13-0702-Rev. K, 20	)-May-13			•			

Revison: 20-May-13 Document Number: 71655



### RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Dual



Recommended Minimum Pads Dimensions in Inches/(mm)

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Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000